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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Mezenner

Art Unit: 2873

Serial No.: 10/749,277

Examiner: Dinh, Jack

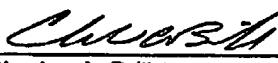
Filed: 31 December 2003

Docket No. TI-33824

For: VIA ADHESION IN MULTILAYER MEMS STRUCTURE

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NAME OF INVENTOR(S):	
Mezenner	
TITLE OF INVENTION:	
VIA ADHESION IN MULTILAYER MEMS STRUCTURE	
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TI-33824	20-0668
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